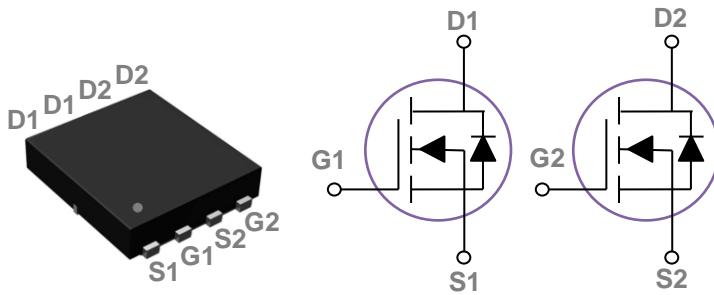


General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

PPAK5x6 Dual Pin Configuration



BVDSS	RDS(ON)	ID
40V	9mΩ	30A

Features

- 40V,30A, RDS(ON) =9mΩ@VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- MB / VGA / Vcore
- POL Applications
- SMPS 2nd SR
- USB Type C

Absolute Maximum Ratings T_c=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	40	V
V _{Gs}	Gate-Source Voltage	±20	V
I _D	Drain Current – Continuous (T _c =25°C)	30	A
	Drain Current – Continuous (T _c =100°C)	19	A
I _{DM}	Drain Current – Pulsed ¹	120	A
EAS	Single Pulse Avalanche Energy ²	64	mJ
IAS	Single Pulse Avalanche Current ²	36	A
P _D	Power Dissipation (T _c =25°C)	46	W
	Power Dissipation – Derate above 25°C	0.37	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to ambient	---	62	°C/W
R _{θJC}	Thermal Resistance Junction to Case	---	2.7	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)
Static State Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	40	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=40\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=32\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ³	$V_{\text{GS}}=10\text{V}$, $I_D=8\text{A}$	---	7.2	9	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=4\text{A}$	---	9.5	12	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	1	1.6	2.5	V
g_{fs}	Forward Transconductance	$V_{\text{DS}}=10\text{V}$, $I_D=10\text{A}$	---	13	---	S

Dynamic Characteristics

Q_g	Total Gate Charge ^{3, 4}	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=8\text{A}$	---	12.2	24	nC
Q_{gs}	Gate-Source Charge ^{3, 4}		---	3.3	7	
Q_{gd}	Gate-Drain Charge ^{3, 4}		---	6.7	13	
$T_{\text{d(on)}}$	Turn-On Delay Time ^{3, 4}	$V_{\text{DD}}=15\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=3.3\Omega$	---	13.2	25	ns
T_r	Rise Time ^{3, 4}		---	2.2	5	
$T_{\text{d(off)}}$	Turn-Off Delay Time ^{3, 4}		---	72	130	
T_f	Fall Time ^{3, 4}		---	4.5	10	
C_{iss}	Input Capacitance	$V_{\text{DS}}=25\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	1220	2200	pF
C_{oss}	Output Capacitance		---	130	250	
C_{rss}	Reverse Transfer Capacitance		---	55	110	
R_g	Gate resistance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $F=1\text{MHz}$	---	2.2	---	Ω

Guaranteed Avalanche Energy

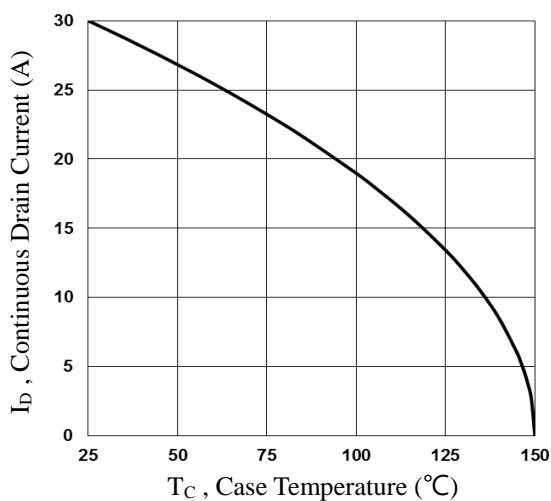
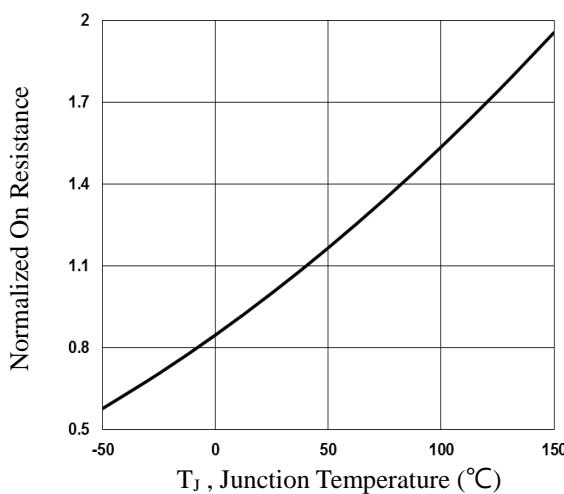
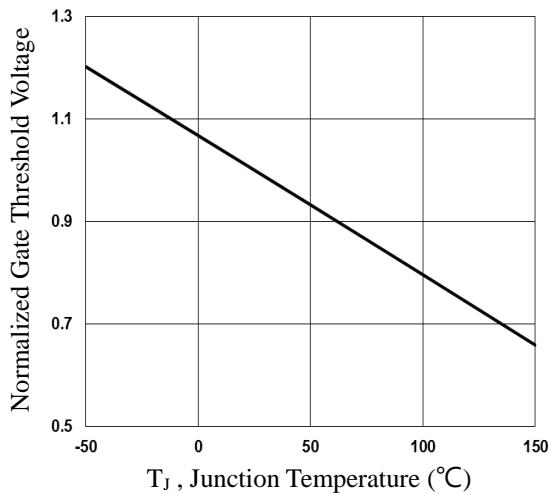
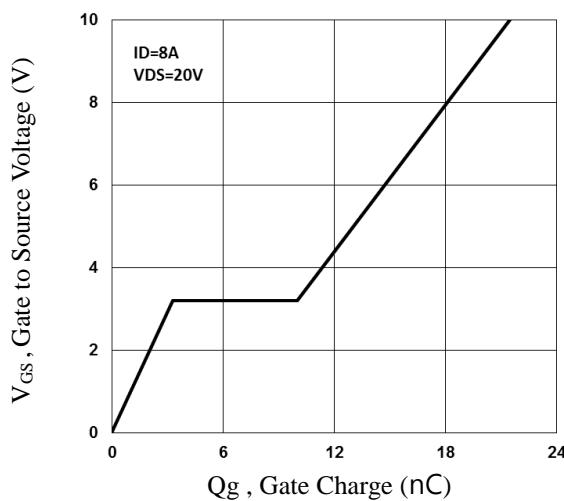
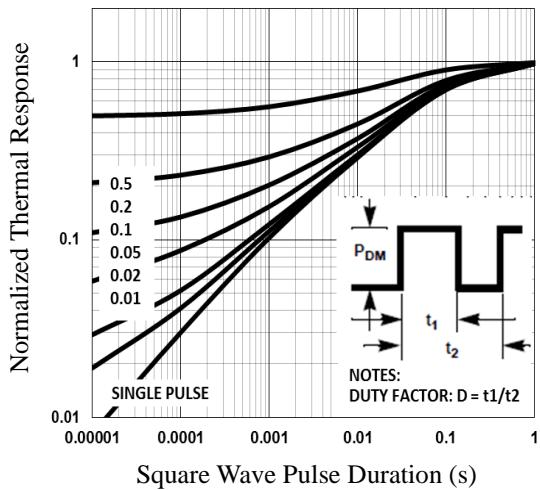
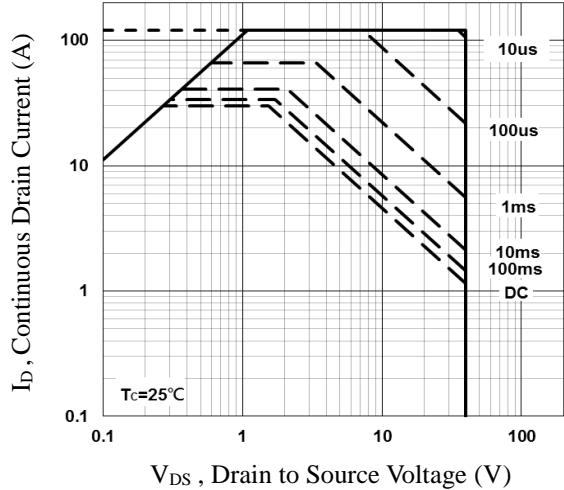
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy	$V_{\text{DD}}=25\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=6\text{A}$	1.8	---	---	mJ

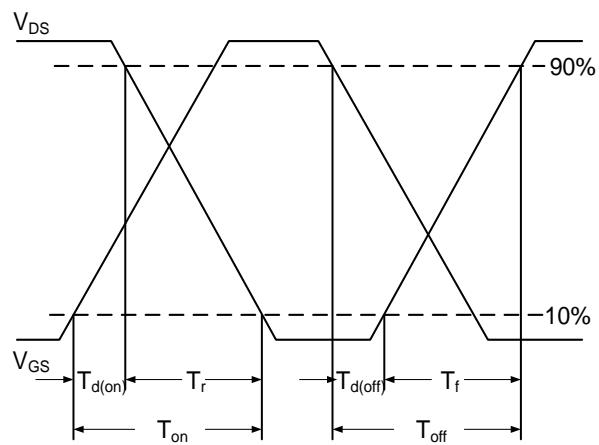
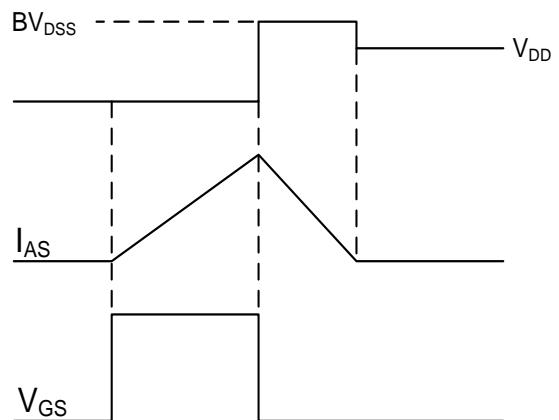
Drain-Source Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	30	A
I_{SM}	Pulsed Source Current ³		---	---	60	A
V_{SD}	Diode Forward Voltage ³	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V

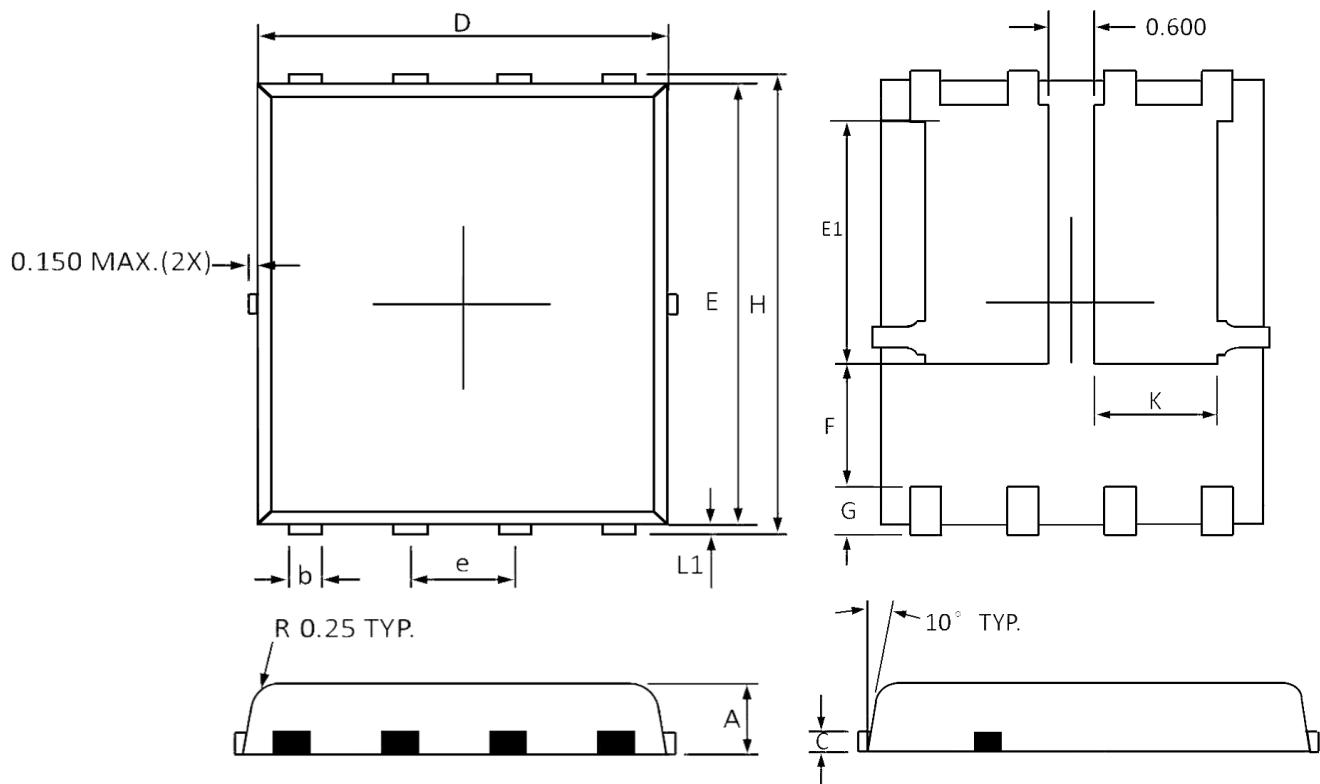
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=36\text{A}$, $R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$.
3. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. T_c

Fig.2 Normalized RDSON vs. T_j

Fig.3 Normalized V_{th} vs. T_j

Fig.4 Gate Charge Waveform

Fig.5 Normalized Transient Impedance

Fig.6 Maximum Safe Operation Area


Fig.7 Switching Time Waveform

Fig.8 EAS Waveform

PPAK5x6 Dual PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.800	1.200	0.031	0.047
b	0.300	0.510	0.012	0.020
C	0.250 Ref		0.010 Ref	
D	4.800	5.400	0.189	0.213
E	5.450	5.960	0.215	0.235
E1	3.200	3.800	0.126	0.150
e	1.27 BSC		0.050 BSC	
F	1.000	1.900	0.039	0.075
G	0.380	0.800	0.015	0.031
H	5.850	6.300	0.230	0.248
L1	0.050	0.250	0.002	0.010
K	1.500	1.900	0.059	0.074

PPAK5X6 Dual RECOMMENDED LAND PATTERN